

ANGI064072-P51

C-band matched GaN Device

Features:

Frequency: 6.4~7.2GHz

Saturated Output Power: Psat≥51dBm

PowerGain: Gain≥9dB

Add-Efficiency: PAE≥40%

Port Matching: $Z_{in}/Z_{out} = 50\Omega$

Description:

ANGI064072-P51 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 6.4~7.2GHz. This device can be used in different RF/Microwave system and subsystem.

The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Maximun Ratings (TC=25°C, Not recommended working under this condition):

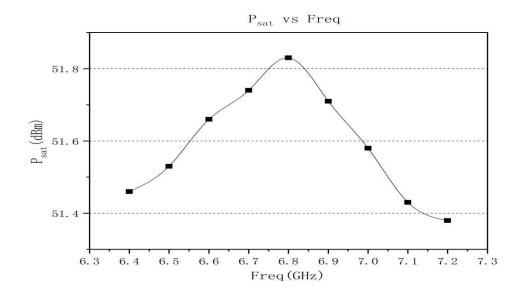
	Symbol	Value	Unit
Voltage between source and drain	V DS	40	V
Voltage between gate and source	V _G s	-5	V
Storage Temperature Range	T_{stg}	-65 to +175	°C
Drain and Source Channel Temperature	Tch	175	°C



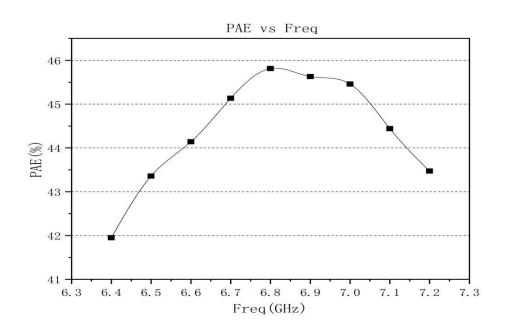
Electrical Characteristics:

				Value		
	Symbol	Test condition	Min	Тур	Max	Unit
Drain Current	ldsr		-	10.2	-	А
Saturated Output Power	Psat	Vds=28V PW.	51	-	-	dBm
Gain	T=1ms, Duty=109 Gp Pin: 42dBm	9	-	-	dB	
Add-Efficiency	PAE	Freq: 6.4~7.2GHz	40	ı	ı	%
Gain Flatness	ΔG		-0.8	-	+0.8	dB

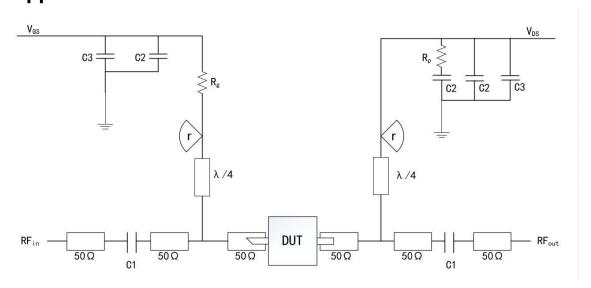
Typical Curve:



Internal Matching GaN Device



Application Circuit:



DUT: Device to be tested

C1:3pF R_p :51 Ω

C2:1000pF $R_G:15\Omega$

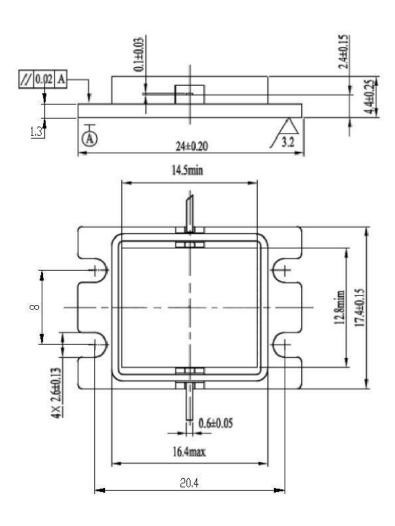
C3:100uF r(radius)≈4.5mm(Rogers5880, 20mil)



ESD Level:

ESD	Class III	2000V

Outline:



Precautions for use:

- Pay attention to drying transportation and storage.
- Pay attention to anti-static during chip use and assembly, and wear grounding anti-static bracelet.
- When powering up, first apply grid power then add leakage.